

Pb-free solder paste for IPC-L0 standard SL100



SL100 is a high reliable lead-free solder paste satisfies IPC-L0 standard. It has excellent viscosity stability in storage and production, contributing to reduced defects and improved productivity in the SMT process.

■ Solder paste classification

Solder composition	SnPb	SAC305	High durable	Low melting point
Powder size	Type4 (20 – 38μm)	Type5 (15 – 25μm)	Type6 (5-15μm)	Type7 (2-11μm)
IPC-Flux type	L0	L1	M0	M1
Reflow condition	Air	Nitrogen		

■ Features

- SAC305 lead-free solder paste that meets IPC –L0 standard
- Viscosity change during continuous printing is less, achieving a long period pf production.
- Two categories for Type4 and Type5 powder size are available to achieve joining a variety of electronic components.
- Support both air reflow and nitrogen reflow conditions.

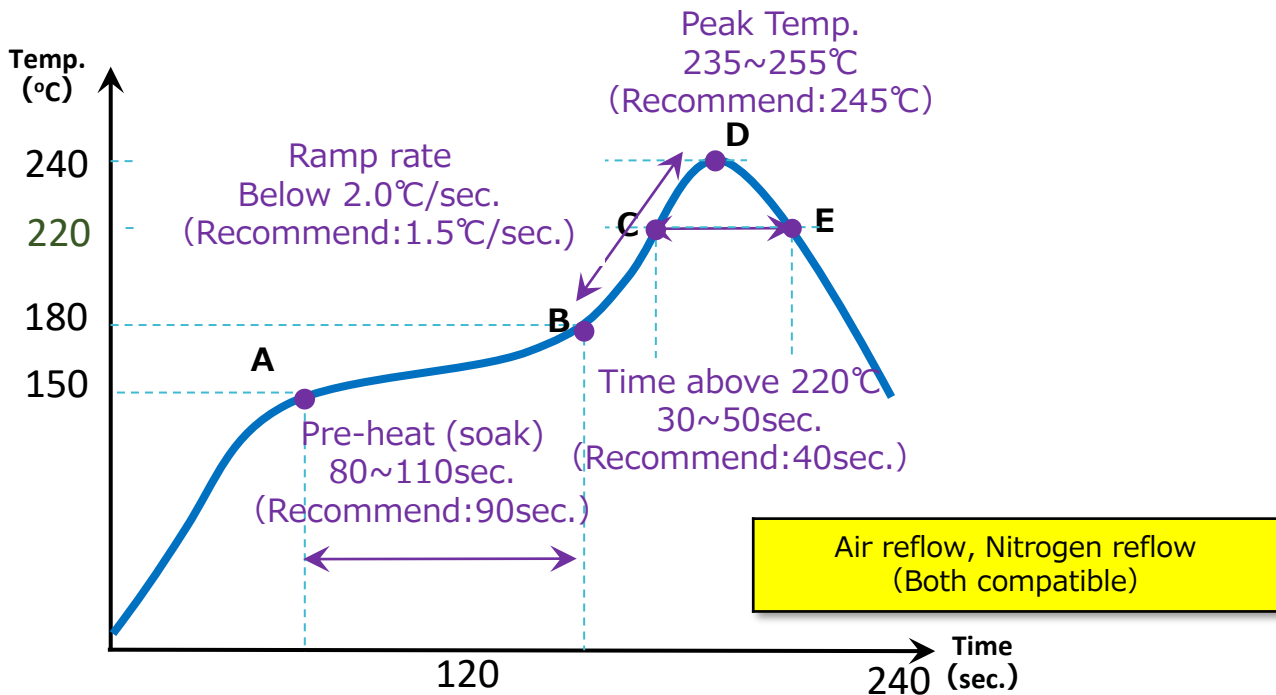
■ Properties (representative value)

		性能 (代表値)		備考
Product name		PS31BR-600-SL100	PS31BR-700-SL100	–
Alloy composition		Sn-3.0Ag-0.5Cu		–
Powder size		20-38μm(Type4)	15-25μm(Type5)	IPC J-STD-005A
Flux type		ROLO		IPC J-STD-004B
Solidus temp.		217℃		JIS Z 3198-1
Liquidus temp.		219℃		
Halide content		0.0%		IPC-TM-650
Flux content		11.5%		–
Copper corrosion		No corrosion		40℃×90% 72h
Surface insulation resistance		> 1×10 ⁹ Ω		85℃×85% 1,000h
Migration		No migration		Apply:50V Measure : 100V
Dryness		No tackiness (Flux residue)		–
Viscosity property	Viscosity	200Pa·s	210Pa·s	JIS Z 3284-3
	Thixotropic index	0.50	0.50	
Slump in printing		<0.2mm gaps		
Slump in heatin		<0.2mm gaps		
Tackiness		> 1.0N(0~24h)		
Flux efficacy / De-wetting		Class2 / No de-wetting		
Solder Ball		Class2(0, 24h)		JIS Z 3284-4
Shelf life		6 months		Storage(0~10℃)

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Recommended reflow profile



Precautions for handling

(1) Storage conditions

- 1) Store between 0 and 10°C.
- 2) Avoid exposing to direct sunlight.
- 3) Confirm the lid is closed firmly before storage.

(2) Cautions for handling

- 1) Avoid the handling of solder paste other than operator.
- 2) Wear appropriate gloves and glasses to use solder paste.
- 3) Wipe off solder paste with ethanol when it adheres to your skin.
- 4) Wash hands well after handling solder paste.
- 5) Set up a ventilation system at the handling place.

(3) Usage Instructions

- 1) Do not open the container until solder paste reaches to room temperature.
 - * Solder paste quality will be deteriorated due to water condensation if you open the lid before getting to room temperature.
 - * Avoid rapid heating, such as using heater.
- 2) Stir solder paste well before using.
- 3) Do not use solder paste with any other kind of solder paste or solvent.
- 4) Avoid using used solder paste mixed with fresh solder paste.
- 5) Recommended conditions for usage: temperature 22 to 28 °C and humidity 50% RH.